PCN Number:	20231004001.1	**PCN Date:**	October 05, 2023
Title:	Qualification of RFAB as an additional Fab site option for select HPA07 devices		
Customer Contact:	Change Management team	**Dept:**	Quality Services
Proposed 1st Ship Date:	Jan 5, 2024	**Sample requests accepted until:**	November 5, 2023*

***Sample requests received after November 5, 2023 will not be supported.**

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☐	Assembly Materials	☐	Part number change	☒	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☒	Wafer Fab Material
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the addition of RFAB as an additional Wafer Fab site option for the products listed in the "Product Affected" section of this document.

Current Fab Site			New Fab Site		
Current Fab Site	**Process**	**Wafer Diameter**	**New Fab Site**	**Process**	**Wafer Diameter**
AIZU	HPA07	200mm	RFAB	HPA07	300mm

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

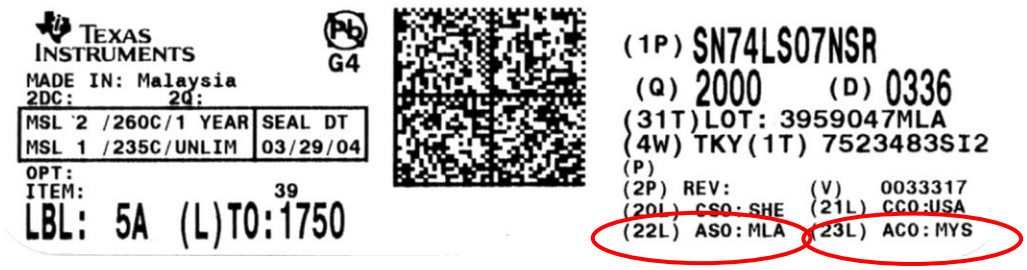
None

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
AIZU	CU2	JPN	Aizuwakamatsu-shi
RFAB	**RFB**	**USA**	**Richardson**

Sample product shipping label (not actual product label)



Product Affected:

OPA2376AID	OPA2376AIDR	OPA2377AIDGKT	TLV2376IDGKT
OPA2376AIDGKR	OPA2377AID	OPA2377AIDR	TLV2376IDR
OPA2376AIDGKT	OPA2377AIDGKR	TLV2376IDGKR	

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: OPA2376AIDGKR	Qual Device: OPA2376AIDR	Qual Device: OPA2377AID	QBS Process Reference: CD3232A1YFFR	QBS Process Reference: CD3232A1YFFR	QBS Process Reference: AMC7836IPAP	QBS Process Reference: DRV401AIRGWR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	3/231/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	3/231/0	-	-
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	-	-	-	3/231/0	3/231/0	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	3/231/0	3/231/0	-	-
HTOL	B1	Life Test	140C	480 Hours	-	-	-	1/77/0	2/154/0	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	-	-	1/77/0	2/154/0
ELFR	B2	ELFR	125C	48 Hours	-	-	-	1/1000/0	2/2000/0	-	-
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	-	1/3/0	-	-	1/3/0	2/6/0
ESD	E2	ESD CDM	-	200 Volts	-	-	-	-	3/9/0	-	-
ESD	E2	ESD CDM	-	250 Volts	-	-	-	2/6/0	-	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	1/3/0	2/6/0	3/9/0	-	2/6/0
ESD	E2	ESD HBM	-	2500 Volts	-	-	-	-	-	1/3/0	-
ESD	E2	ESD HBM	-	4000 Volts	-	-	1/3/0	-	-	-	-
LU	E4	LU	Per JESD78	-	-	-	-	2/6/0	3/9/0	-	-
LU	E4	Latch-Up	Per JESD78	-	-	-	1/3/0	-	-	1/3/0	2/6/0[2,3]
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30	1/30/0	-	1/30/0	1/30/0	1/30/0	1/30/0
FTY	E6	Final Test Yield	-	-	1/Pass	1/Pass	1/Pass	-	-	-	-

- QBS: Qual By Similarity
- Qual Device OPA2376AIDGKR is qualified at MSL2 260C
- Qual Device OPA2376AIDR is qualified at MSL2 260C
- Qual Device OPA2377AID is qualified at MSL2 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2305-068

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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